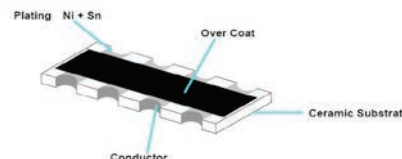


MATERIAL DECLARATION SHEET



Material Number	CAY17-JA (LF)		
Product Line	Chip Resistor Array		
Compliance Date	4-1-2003 DC0314		
RoHS Compliant	Yes	MSL	1



No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.0069790704	Aluminum oxide	1344-28-1	96%	77.12%	80.33%
				Crystalline Silica Quartz	14808-82-7	4%	3.2%	
2	Conductor Layer	Conductor Ink	0.0002059056	Silver	7440-22-4	95%	2.25%	2.37%
				Glass	65997-18-4	5%	.12%	
3	Resistive Element	Resistive Ink	0.0000973056	Ruthenium oxide	12036-10-1	25%	0.28%	1.12%
				Silver	7440-22-4	40%	0.45%	
				Palladium	7440-5-3	15%	0.17%	
				Glass	1317-36-8	20%	0.22%	
4	Over-Coating	Epoxy	0.0001251072	Epoxy	25068-38-6	100%	1.44%	1.44%
5	Marking	Epoxy	0.0000034752	Epoxy	25068-38-6	100%	0.04%	0.04%
6	End Terminal	Ni-Cr	0.0002571648	Nickel	7440-02-0	80%	2.37%	2.96%
				Chromium	7440-47-3	20%	0.59%	
7	Nickel Plating	Metal	0.000560376	Nickel	7440-02-0	100%	6.45%	6.45%
8	Tin Plating	Metal	0.0004595952	Tin	7440-31-5	100%	5.29%	5.29%
			Total weight	0.008688				

This Document was updated on: **04-11-2016**

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I